

IRPS 2024 Technical Program Committee

<p style="text-align: center;">Circuit Reliability and Aging</p> <p>Alberto Bosio, University of Lyon Enrique Carrion, Google Rafael Castro Lopez, IMSE-CNM Albert Crespo Yepes, Universitat Autònoma de Barcelona Jeff Gambino, Onsemiconductor Richard Heller, AMD Mitsuhiro Igarashi, Renesas Electronics Biresh Kumar Joardar, University of Houston Saibal Mukhopadhyay, Georgia Institute of Technology Vijay Reddy, Texas Instruments Mehdi Sadi, Auburn University Hyewon Shim, Samsung Victor M. van Santen, University of Stuttgart Mustafa Berke Yelten, Istanbul Technical University</p>	<p style="text-align: center;">Process Integration</p> <p>Cheikh Diouf, ST Microelectronics Alexander Grill, IMEC L S Huang, umc Jen-Hao Lee, TSMC Chandra Mandalapu, AMD Andreas Martin, Infineon Hiroshi Miki, Rapidus Mustapha Rafik, Aledia Rakesh Ranjan, Samsung Hyunchul Sagong, KATECH Guido Sasse, Nxp Motoyuki Sato, Tokyo Electron Lieyi Sheng, onsemi Alexandre Subirats, Micron</p>	
<p style="text-align: center;">Emerging Memory</p> <p>Pei-Ying Du, Macronix Davide Fugazza, Intel Laurent Grenouillet, CEA-Leti Keizo Hiraga, Sony Guohan Hu, IBM Seyoung Kim, Postech Kai Ni, University of Notre Dame Barry O'Sullivan, IMEC Jaeyun Yi, SK hynix</p>	<p style="text-align: center;">Product Reliability</p> <p>Davide Appello, Technoprobe Jyotika Athavale, Synopsys Sandhya Chandrashekhar, Google Ryan Lu, TSMC Richard Rao, Marvel Mihaela (Maria) Tanasescu, AMD Xinggong Wan, Globalfoundries</p>	
<p style="text-align: center;">ESD and Latchup (IRPS)</p> <p>Dolphin Abessolo Bidzo, NXP Shih-Hung Chen, IMEC ChanHee Jeon, Samsung Mirko Scholz, Infineon Technologies Teruo Suzuki, Socionext</p>	<p style="text-align: center;">ESD and Latchup (IEW)</p> <p>Prantik Mahajan, Renesas Slavica Malobabic, Cirrus Logic Bill Moore, Skyworks Scott Ruth, AMD Michael Stockinger, NXP</p>	<p style="text-align: center;">Radiation Effect Reliability</p> <p>Laurent Artola, ONERA Sang Baeg, Hanyang University Indranil Chatterjee, Airbus Li Chen, University of Saskatchewan Gilles Gasiot, ST Microelectronics Masanori Hashimoto, Kyoto University Bo Li, Institute of Microelectronics, Chinese Academy of Sciences Nihaar Mahatme, NXP Pierre Maillard, AMD Taiki Uemura, Samsung</p>

<p style="text-align: center;">Failure Analysis</p> <p>Yong Guo, Samsung Pinakpani Nayak, Intel Daniel Sullivan, EAG Laboratories Bryan Tracy, Tesla</p>	<p style="text-align: center;">Reliability Testing</p> <p>Yanjun Feng, Canoo Inc. Martina Hommel, Robert Bosch GmbH Bob Keller, NIST Jin Soak Kim, Samsung Linfei (Jamie) Li, Cadence Kevin Manning, Analog Devices Fiorella Pozzobon, ST Microelectronics Yiming Qu, East China Normal University Dirk Rudolph, Globalfoundries Derek Slotke, Intel Wangran Wu, Southeast University Zhao Yi, Zhejiang University</p>
<p style="text-align: center;">GaN Devices</p> <p>Julien Buckley, CEA Leti Kevin J Chen, HKUST Okita Hideuki, Panasonic Christian Koller, Infineon Ethan Lee, Texas Instruments Matteo Meneghini, University of Padova Kurt Smith, VisIC Technologies Tsutomu Uesugi, Nagoya University Shuzhen You, Xidian University</p>	<p style="text-align: center;">RF/mmW/5G</p> <p>Karim Boutros, Boeing Michael Dammann, Fraunhofer Institute Alexis Divay, CEA Leti Gergana Drandova, Qorvo Xavier Federspiel, ST Microelectronics Farid Medjdoub, CNRS Vijay Reddy, Texas Instruments Rosana Rodriguez, Universitat Autònoma de Barcelona Hao Yu, IMEC Enrico Zanoni, University of Padua</p>
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<p style="text-align: center;">Metallization/BEOL Reliability</p> <p>Arief Budiman, Oregon Institute of Technology Kristof Croes, IMEC Gavin Hall, Infineon Sumy Jose, NXP Ki-Don Lee, Samsung Farid Najm, University of Toronto Atsushi Ogino, IBM Valeriy Sukharev, Siemens EDA Ping-Chuan Wang, SUNY New Platz Shinji Yokogawa, UEC</p>	<p style="text-align: center;">System Electronics Reliability</p> <p>Jyotika Athavale, Synopsys Timothy Ayles, Airbus Brad Bittel, Intel Ivan Ciofi, IMEC Yi-Ching (YC) Ong, TSMC Nikolaos Papandreou, IBM Research Zurich Rich Pietri, Apple Jay Sarkar, Micron Emma Schmidgall, Microsoft David Sunderland, Boeing (<i>retired</i>)</p>
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